

Performance Specification

Model	I _{hold} (A)	I _{trip} (mA)	V _{max interup} (tV)	I _{max} (A)	Pd _{max} (W)	Maximum Time to Trip		Resistance(Ω)
						Current (A)	Time (S)	R _{min} - R _{max}
JK130-010	0.10	0.20	130	3	0.8	0.5	6	2.5-9.0
JK130-015	0.15	0.30	130	3	0.8	0.75	5.5	2.5-7.5
JK130-017	0.17	0.34	130	3	0.8	0.85	5.2	1.5-7.0
JK130-020	0.20	0.40	130	3	0.8	1.0	5.0	1.9-4.0
JK130-025	0.25	0.50	130	3	1.0	1.25	4.8	1.45-3.50
JK130-030	0.30	0.60	130	3	1.0	1.5	4.5	1.0-3.0
JK130-040	0.40	0.80	130	3	1.0	2.0	4.5	0.75-2.0
JK130-050	0.50	1.0	130	3	1.0	2.5	5.0	0.50-1.60
JK130-065	0.65	1.3	130	10	1.0	3.25	5.2	0.45-1.0
JK130-075	0.75	1.5	130	10	1.0	3.75	5.5	0.40-0.90
JK130-090	0.90	1.8	130	10	1.5	4.5	5.8	0.30-0.70
JK130-110	1.10	2.2	130	10	1.8	5.5	6.3	0.20-0.65
JK130-135	1.35	2.7	130	10	1.8	6.75	7.5	0.15-0.60
JK130-160	1.60	3.2	130	10	2.0	8.0	8	0.10-0.50
JK130-185	1.85	3.7	130	10	2.0	9.25	9	0.10-0.40
JK130-200	2.00	4.0	130	10	2.2	10.0	10	0.10-0.30
JK130-250	2.50	5.0	130	10	2.5	12.5	12	0.05-0.25

V_{max} = Maximum operating voltage device can withstand without damage at rated current (I_{max}).

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max}).

I_{hold} = Hold Current. Maximum current device will not trip in 25°C still air.

I_{trip} = Trip Current. Minimum current at which the device will always trip in 25°C still air.

Pd = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

R_{i min/max} = Minimum/Maximum device resistance prior to tripping at 25°C.

R_{1max} = Maximum device resistance is measured one hour post reflow.

CAUTION : Operation beyond the specified ratings may result in damage and possible arcing and flame.

Physical Dimensions(mm.)

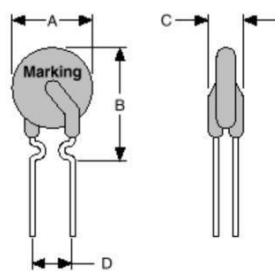


Fig.1

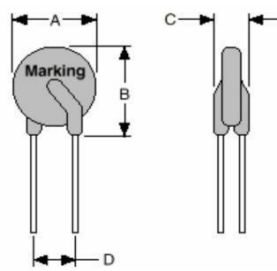


Fig.2

Model	Dimensions (mm)				Lead material Tinned matel(mm)	Shape Fig
	A(max)	B(max)	C(max)	D(typ)		
JK130-010	7.4	12.7	3.8	5.1	22AWG/Φ0.6	1
JK130-015	7.4	13.0	3.8	5.1	22AWG/Φ0.6	1
JK130-017	7.4	13.5	3.8	5.1	22AWG/Φ0.6	1
JK130-020	7.6	13.5	3.8	5.1	22AWG/Φ0.6	1
JK130-025	7.6	13.5	3.8	5.1	22AWG/Φ0.6	1
JK130-030	8.0	14.0	3.8	5.1	22AWG/Φ0.6	1
JK130-040	9.4	15.0	3.8	5.1	22AWG/Φ0.6	1
JK130-050	10.2	15.2	3.8	5.1	22AWG/Φ0.6	1
JK130-065	12.8	18.0	3.8	5.1	22AWG/Φ0.6	1
JK130-075	12.8	18.0	3.8	5.1	22AWG/Φ0.6	1
JK130-090	14.5	19.6	3.8	5.1	20AWG/Φ0.8	2
JK130-110	16.3	21.3	3.8	5.1	20AWG/Φ0.8	2
JK130-135	17.0	22.0	3.8	5.1	20AWG/Φ0.8	2
JK130-160	20	25	3.8	5.1	20AWG/Φ0.8	2
JK130-185	22	23	3.8	5.1	20AWG/Φ0.8	2
JK130-200	25	27	3.8	10.2	20AWG/Φ0.8	2
JK130-250	27	32	3.8	10.2	20AWG/Φ0.8	2

Note: ① Dimensions A, B, C is the maximum size, D values are typical tolerance of ± 0.75 mm.

Environmental Specifications

Test	Conditions	Resistance change
Passive aging	+85°C, 1000 hrs.	$\pm 5\%$ typical
Humidity aging	+85°C, 85% R.H. , 168 hours	$\pm 5\%$ typical
Thermal shock	+85°C to -40°C, 20 times	$\pm 33\%$ typical
Resistance to solvent	MIL-STD-202, Method 215	No change
Vibration	MIL-STD-202, Method 201	No change

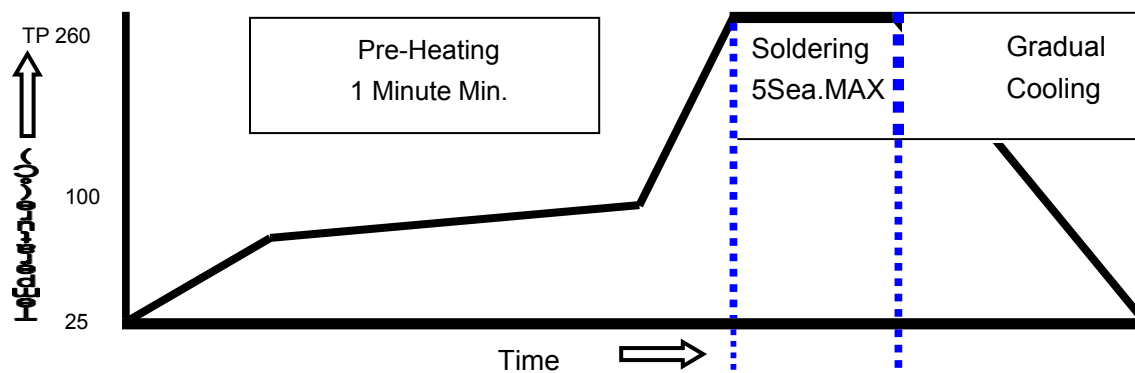
Ambient operating conditions : - 40 °C to +85 °C

Maximum surface temperature of the device in the tripped state is 125 °C

Hold Versus Temperature

Model	Maximum ambient operating temperatures (°C)									
	-40°C	-20°C	0°C	25°C	30°C	40°C	50°C	60°C	70°C	85°C
JK130 series	147%	132%	118%	100%	90%	85%	76%	67%	60%	47%

Soldering Parameters



WAVE SOLDERING INFORMATION

Pre-Heating Zone	Max. ramping rate should not exceed 4°C/Sec.
Soldering Zone	Max. solder temperature should not exceed 260°C
Cooling Zone	Cooling by natural convection in air.

© Specifications are subject to change without notice.

Packaging Quantity

JK130-010~JK130-065	1000Pcs/Bag
JK130-075~JK130-200	500 Pcs/Bag

Website: <http://www.jksemi.com>

For additional information, please contact your local Sales Representative.

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